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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Walter SCHWARZENBACH et al. Confirmation No.: 3337
Application No.: 10/766,207 Group Art Unit: 2822
Filing Date: January 29, 2004 Examiner: Khanh B. Duong
For: METHOD OF DETACHING A LAYER FROM A WAFER USING A LOCALIZED STARTING AREA Attorney Docket No.: 4717-11600

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action mailed September 20, 2005, Applicants respectfully request entry of the following amendments and remarks into the file of this application.

Amendments to the Specification appear on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks begin on page 6 of this paper.

A Supplemental Information Disclosure Statement is enclosed.

A Certified Copy of the priority document is also enclosed.

No fee is believed to be due for the claim changes and additions of this submission. Please charge any and all required fees to **Winston & Strawn LLP** Deposit Account No. 50-1814.